MaxShield EMI Shielding Material

TennVac
EMI / Thermal
http://www.tennvac.com

Conductive Form-In-Place Gasket F5304

Description

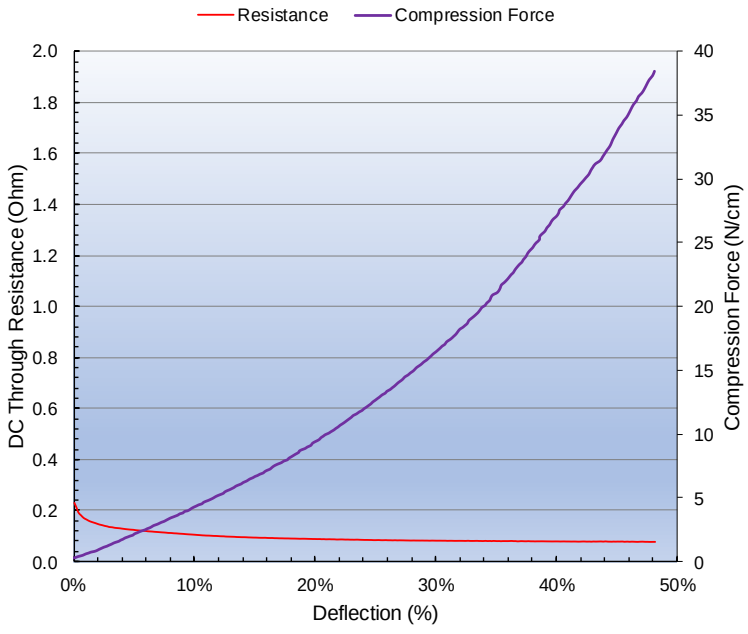
The conductive Form-In-Place material F5304 with Ultrasoft has great compression and excellent conductivity. This will reduce mechanical requirements and is ideal for most application.

The F5304 offers enhanced galvanic corrosion resistance and stability in severe environments.

Benefits

- Extremely soft gasket profile in Ni/Gr filled family.
- Less compression force required
- More than 100 dB shielding effectiveness from 200MHz to 40GHz with a small gasket bead
- Accuracy for gasket location within 0.001" (0.025 mm)
- More than 80 Newtons/cm² shear adhesion on common housing substrates and coatings

Force-Deflection-Resistance of F5304 Gasket
D Shape 1.0 mm(H) * 1.3 mm(W) * 5.0 mm(L)
Rate of Strain, 1.5mm/min



Properties	Unit	F5304
Elastomer Binder		Silicone
Conductive Filler		Ni/Gr
Cure System		Thermal
Density	g/cm^3	2.0
Hardness	Shore A	30
Adhesion on Al metal	N/cm^2	>80
Tensile Strength	psi	120
Elongation	%	100
Tear Strength	lbf/in	30
Compression Set @70°C ,72 hrs.	%	25
Temperature Range	°C	-45 to 150
Maximum Using Temperature	°C	200
UL Flammability Rating	UL94 V-0	E303387
DC-Through Resistance, 30% compression,1mmH	Ohm	0.08
Shielding Effectiveness 200 MHz ~ 40 GHz	dB	>100

REV.1.0

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